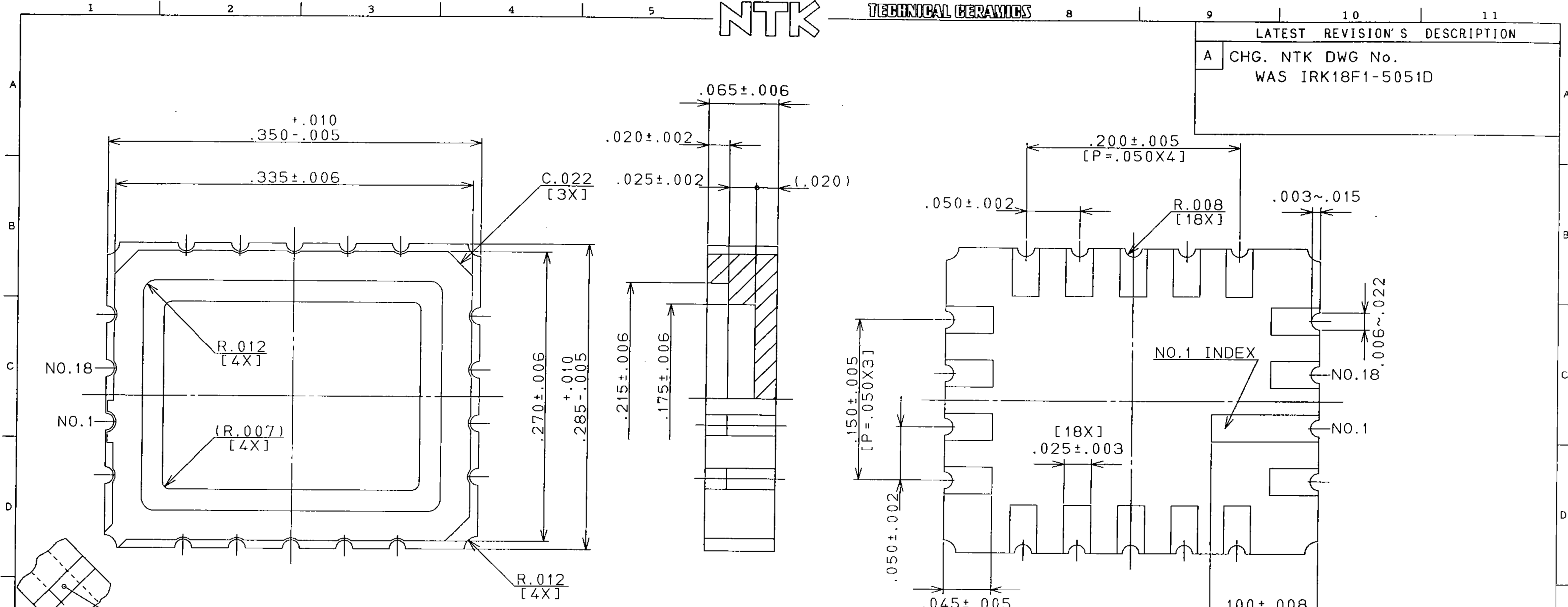
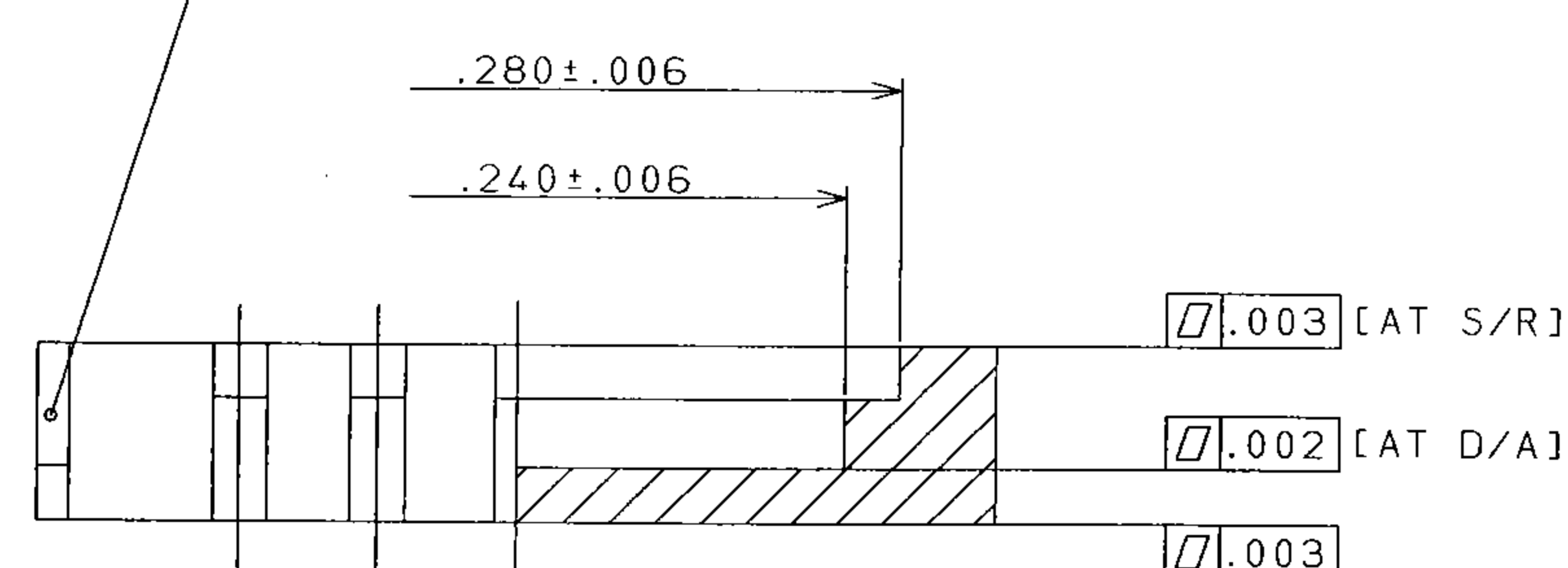


A CHG. NTK DWG No.
WAS IRK18F1-5051D



THIS METALLIZATION ELECTRICALLY CONNECTED TO THE SEAL RING.



NOTES:

1. GOLD PLATE 60μ INCHES MIN OVER 100μ INCHES MIN NICKEL.
2. NO LEAD TO BE ELECTRICAL CONNECTED TO THE DIE ATTACH PAD. SEAL RING ISOLATED.
3. LEAD RESISTANCE : 300mΩ MAX

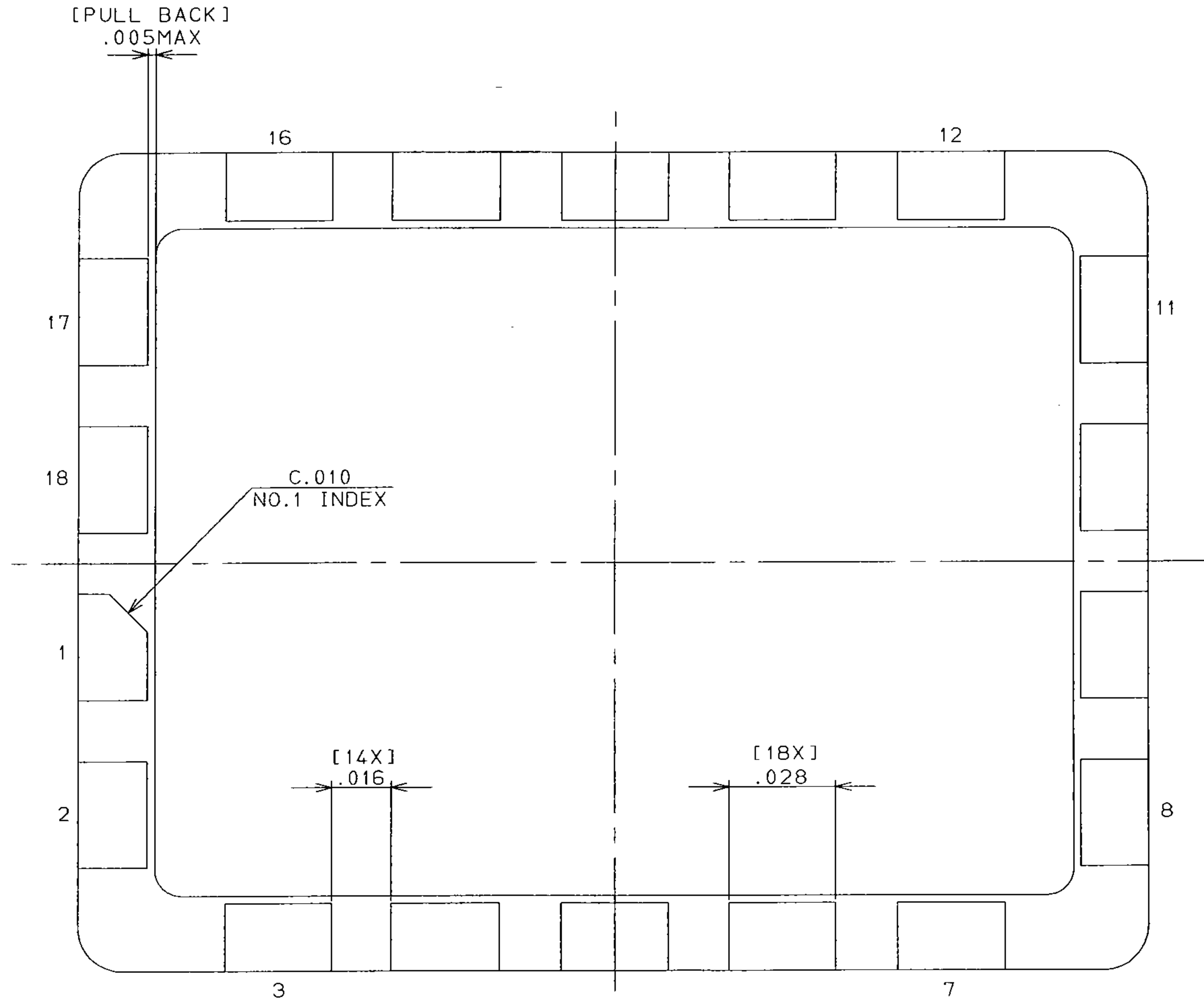
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98.4.17
*技術部

OPEN-TOOLE

MODIFIED
DWG NO.

3					
2					
1	CERAMIC	BLACK ALUMINA		A	RE DRAWING APR.-17-1998
				φ	NEW DRAWING APR.-07-1998
Item	Name	Material	Description	Rev.	Description
UNLESS OTHERWISE SPECIFIED			DRAWN	T.MIWA	NTK TECHNICAL CERAMICS NGK SPARK PLUG CO., LTD
TOLERANCES: ± 1%			CHECKED	S.NAKAGAKI	
N. L. T. 2 DECIMALS: XX ±.01			APPROVED	S.NAKAGAKI	TITLE
3 DECIMALS: XXX ±.005			CUSTOMER	CHELSEA TECHNOLOGY	18 LEAD CHIP CARRIER
DWG NO.			UNIT	INCH	DWG NO.
			SCALE	/	IRK18F1-5051DA

A CHG. NTK DWG No.
WAS IRK18F1-5051D



OPEN-TOOLE



Rev.	Description	Date
A	RE DRAWING	APR.-17 -1998
φ	NEW DRAWING	APR.-07 -1998

UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1 % N. L. T. 2 DECIMALS .XX ± .01 3 DECIMALS .XXX ± .005	DRAWN T.MIWA CHECKED S.NAKAGAKI APPROVED S.NAKAGAKI	NTK TECHNICAL CERAMICS NGK SPARK PLUG CO., LTD TITLE B/G PADS DETAIL
CUSTOMER CHELSEA TECHNOLOGY DWG NO.	UNIT INCH SCALE /	DWG NO. IRK18F1-5051DA SIZE A-2 (C)

MODIFIED DWG NO.	
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